

NOTES:

1. MATERIAL:

HOUSING: High Temperature Thermoplastic

Terminal: Copper Alloy

Shell: Stainless Steel

2. PLATING:

Terminal:50u" Ni UNDERPLATED OVERALL

G/F PLATED ON CONTACT AREA AND SOLDER AREA

Sheel:30u" Ni UNDERPLATED OVERALL

G/F PLATED ON CONTACT AREA AND SOLDER AREA

3.TECHNICAL SPECIALITY:

RATED VOLTAGE: 30V AC MAX.

CURRENT RATING: 0.5A MAX.

INSULATION RESISTANCE:1000MΩ MIN

CONTACT RESISTANCE:50mΩ MAX

WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES

OPERATING TEMPERATURE: -40°C~+85°C Humidity 80%
R.H MAX

4. DIMENSIONS WITH MARK" * "MUST BE MEASURED BY QC AND IPQC

GENERAL TOLERANCE	DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD					
DIM. TOL.	TITLE: NANO SIM CARD 1.37H PUSH PUSH 有柱					
X						
X.X						
X.XX						
X.XXX						
GENERAL ANGLE:						
±0.35						
±0.15						
±0.10						
±2°						
	DWG. NO.: SIM304-TD7P					DRAWN: MAX
	PART NO.: SIM304-TD7P					CHECKED: ELLA
	UNIT: mm	SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn	APPROVED: WILL